

RELIABILITY REPORT
FOR
ICL7660CSA+T
PLASTIC ENCAPSULATED DEVICES

February 13, 2013

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

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Conclusion

The ICL7660CSA+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX1044 and ICL7660 are monolithic, CMOS switched-capacitor voltage converters that invert, double, divide, or multiply a positive input voltage. They are pin compatible with the industry-standard ICL7660 and LTC1044. Operation is guaranteed from 1.5V to 10V with no external diode over the full temperature range. They deliver 10mA with a 0.5V output drop. The MAX1044 has a BOOST pin that raises the oscillator frequency above the audio band and reduces external capacitor size requirements. The MAX1044/ICL7660 combine low quiescent current and high efficiency. Oscillator control circuitry and four power MOSFET switches are included on-chip. Applications include generating a -5V supply from a +5V logic supply to power analog circuitry. For applications requiring more power, the MAX660 delivers up to 100mA with a voltage drop of less than 0.65V.

II. Manufacturing Information

A. Description/Function:	Switched-Capacitor Voltage Converters
B. Process:	M5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand, Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0701-0747
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	132°C/W
M. Multi Layer Theta Jc:	38°C/W

IV. Die Information

A. Dimensions:	60 X 84 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/1.0%Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 125 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 1.7 \times 10^{-9}$$

$$\lambda = 1.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the M5 Process results in a FIT Rate of 0.34 @ 25C and 5.79 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot NYFAGO003Q D/C 9531, Latch-Up lot NYFAGO001B D/C 9533)

The PS32 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-200mA.

Table 1
Reliability Evaluation Test Results

ICL7660CSA+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	80	0	NYFAGA3B4Q, D/C 1152
	Biased	& functionality	45	0	NYFAGK2B5Q, D/C 1108
	Time = 1000 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.